

What is claimed is:

1. A method of manufacturing a ferroelectric film including crystallizing a raw material including a complex oxide, the method comprising:

5 performing a heat treatment in a first condition in which a predetermined pressure and a predetermined temperature are applied; and

maintaining a second condition, in which a pressure and a temperature lower than the pressure and the temperature in the first condition are applied, after the heat treatment in the first condition,

10 wherein the raw material is crystallized by repeating the heat treatment in the first condition and the maintaining the second condition.

2. The method of manufacturing a ferroelectric film as defined in claim 1,

wherein the heat treatment in the first condition is performed at a pressure at two

15 atmospheres or more and in an atmosphere containing oxygen at a volume ratio of 10% or less.

3. The method of manufacturing a ferroelectric film as defined in claim 1,

wherein the heat treatment in the first condition is performed at a pressure of

20 two atmospheres or more using a rapid thermal annealing method.

4. The method of manufacturing a ferroelectric film as defined in claim 3,

wherein the heat treatment in the first condition is performed in an atmosphere containing oxygen at a volume ratio of 10% or less.

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5. The method of manufacturing a ferroelectric film as defined in claim 1,

wherein the heat treatment in the first condition includes applying a pressure at

two atmospheres or more at least before raising a temperature.

6. A ferroelectric film manufactured by using the method of manufacturing a ferroelectric film as defined in claim 1.

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7. A ferroelectric memory comprising the ferroelectric film as defined in claim 6.

8. A method of manufacturing a ferroelectric capacitor, comprising:
10 forming a lower electrode on a body;
forming a ferroelectric film on the lower electrode by crystallizing a raw material including a complex oxide; and
forming an upper electrode on the ferroelectric film,
wherein the crystallization includes:
15 performing a first heat treatment in a first condition in which a predetermined pressure and a predetermined temperature are applied; and
maintaining a second condition, in which a pressure and a temperature lower than the pressure and the temperature in the first condition are applied, after the heat treatment in the first condition,
20 wherein the heat treatment in the first condition and the maintaining the second condition are repeated.

9. The method of manufacturing a ferroelectric film as defined in claim 8,
wherein the first heat treatment in the first condition is performed at a pressure at
25 two atmospheres or more and in an atmosphere containing oxygen at a volume ratio of 10% or less.

10. The method of manufacturing a ferroelectric film as defined in claim 8,
wherein the first heat treatment in the first condition is performed at a pressure
of two atmospheres or more using a rapid thermal annealing method.

5 11. The method of manufacturing a ferroelectric film as defined in claim 10,
wherein the first heat treatment in the first condition is performed in an
atmosphere containing oxygen at a volume ratio of 10% or less.

10 12. The method of manufacturing a ferroelectric film as defined in claim 8,
wherein the first heat treatment in the first condition includes applying a
pressure at two atmospheres or more at least before raising a temperature.

15 13. The method of manufacturing a ferroelectric capacitor as defined in claim 8,
wherein a second heat treatment, in which a temperature higher than the
temperature in the first condition is applied, is performed at least after forming the
upper electrode.

14. The method of manufacturing a ferroelectric capacitor as defined in claim
13,
20 wherein the second heat treatment is performed at a pressure of two atmospheres
or more.

15. The method of manufacturing a ferroelectric capacitor as defined in claim
13,
25 wherein the second heat treatment is performed by using a rapid thermal
annealing method.

16. The method of manufacturing a ferroelectric capacitor as defined in claim
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wherein the second heat treatment is performed in an atmosphere containing
oxygen at a volume ratio of 10% or less.

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17. A ferroelectric capacitor manufactured by using the method of
manufacturing a ferroelectric capacitor as defined in claim 8.

18. A ferroelectric memory comprising the ferroelectric capacitor as defined in
10 claim 17.